

WOXG/WOXMG SERIES

Glass Passivated Bridge Rectifiers

Reverse Voltage - 50 to 1000 Volts

Forward Current - 1.5 Amperes

Features

- Glass passivated chip
- High surge forward current capability
- Reliable low cost construction utilizing molded plastic technique
- Lead tin plated copper

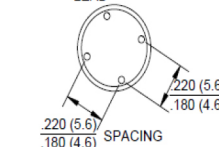
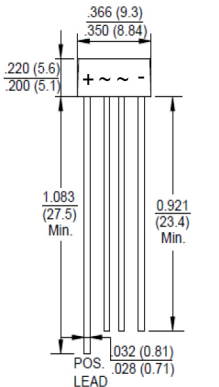
Mechanical Data

- Polarity: Symbol marked on body
- Mounting position: Any

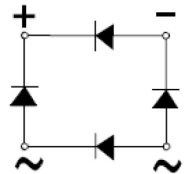
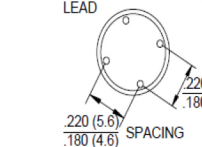
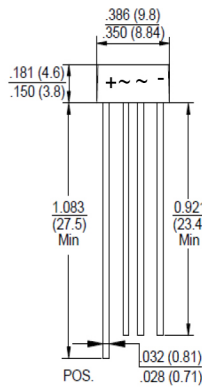
Applications

- General purpose use in AC/DC bridge full wave rectification, for SMPS, lighting ballaster, adapter, etc.

WOB



WOBM



Package Outline Dimensions in Inches (Millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristics	Symbol	W005G	W01G	W02G	W04G	W06G	W08G	W10G	Unit
		W005MG	W01MG	W02MG	W04MG	W06MG	W08MG	W10MG	
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @T _A =25 °C	I _(AV)	1.5							A
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method)	I _{FSM}	40							A
I ² t Rating for Fusing (t<8.3mS)	I ² t	6.64							A ² s
Peak Forward Voltage per Diode at 1.5A DC	V _F	1.1							V
Maximum DC Reverse Current at Rated @T _J =25°C	I _R	10.0							μA
DC Blocking Voltage per Diode @T _J =100°C		1.0							mA
Operating Junction Temperature Range	T _J	-55 to +150							°C
Storage Temperature Range	T _{STG}	-55 to +150							°C

W*G/W*MG-B-00/99-00/01

Rev. 11, 18-May-2020

Rating and Characteristic Curves

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Fig. 1 - Forward Current Derating Curve

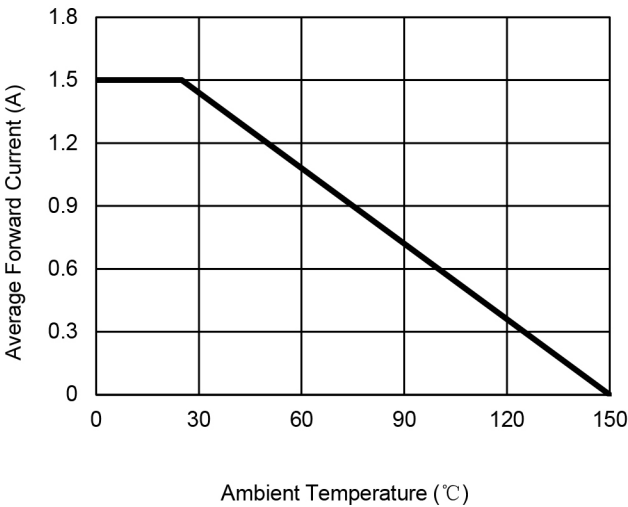


Fig. 2 - Maximum Non-Repetitive Surge Current

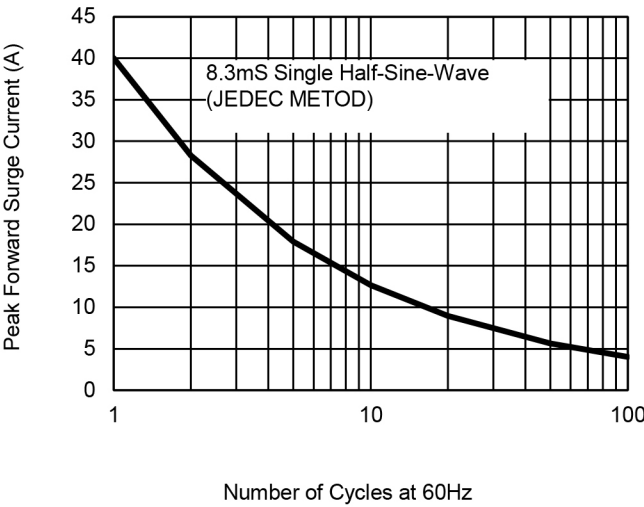


Fig. 3 - Typical Reverse Characteristics

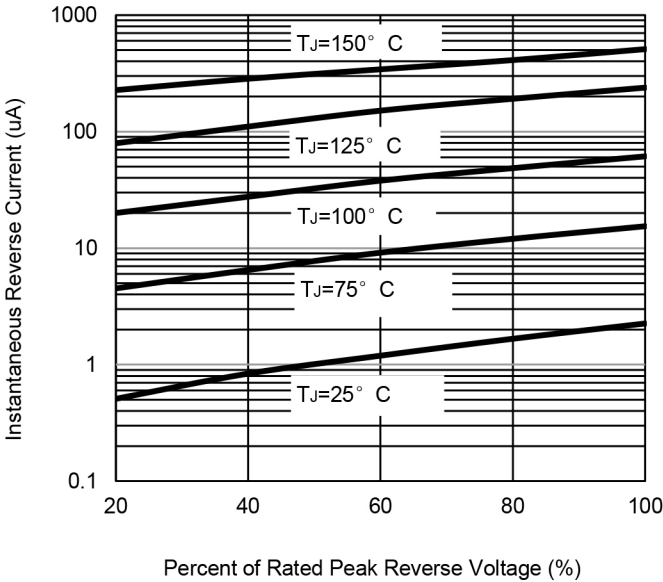
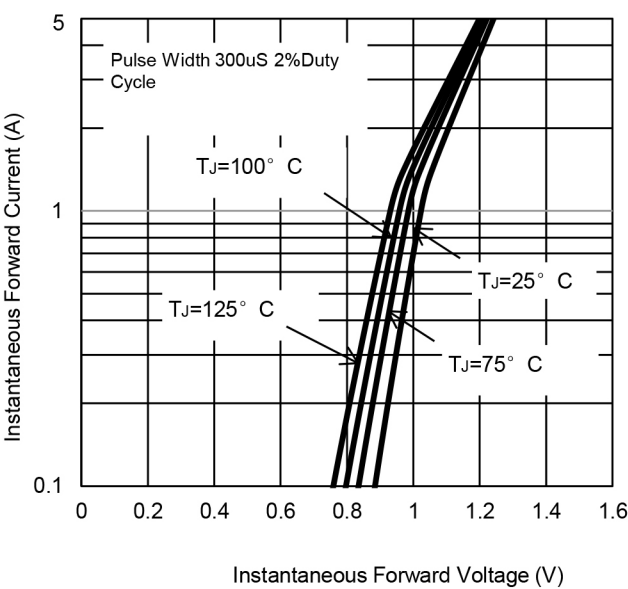


Fig. 4 - Typical Forward Characteristics



The curve above is for reference only.

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